

Appln No. 10/713,076
Amdt. Dated October 15, 2004, 2004
Response to Office action of August 25, 2004

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BEST AVAILABLE COPY**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A composite printhead supporting structure for a pagewidth printhead assembly, the assembly having a plurality of like printhead modules with a predetermined coefficient of thermal expansion, the modules being disposed along a length of the supporting structure, the structure comprising:

a composite beam elongated in the direction of the printhead and being at least as long as the printhead and formed from an odd number of uninterrupted layers, there being a pair of outer layers of equal thickness symmetrically disposed about and laminated to a core, the coefficient of thermal expansion of the core and the outer layers providing a coefficient of expansion, in the beam, substantially equal to that of the modules.

2. (Original) he support structure of claim 1, wherein:

all of the layers are symmetrically disposed about an axis of the beam.

3. (Original) The support structure of claim 1, wherein:

the outer layers are made from invar.

4. (Original) The support structure of claim 1, wherein:

the coefficient of thermal expansion of the outer layers and the core is different.

5. (Currently Amended) The support structure of claim 1, ~~and further comprising the structure being arranged for supporting~~

a plurality of printhead modules positioned at a regular interval along the beam.

6. (Currently Amended) The support structure of claim 5, the structure being arranged for supporting~~wherein:~~

~~the printhead modules are all silicon MEMS type modules.~~

7. (Original) The support structure of claim 1, wherein:

the layers are hot rolled.

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8. (Original) The support structure of claim 7, wherein:
the layers are three in number and the core has a coefficient of thermal expansion greater than that of silicon.
9. (Currently Amended) The support structure of claim 4, wherein:
the coefficient of thermal expansion of ~~one~~the material of the core is greater than that of silicon and the coefficient of thermal expansion of the ~~other material of the outer layers~~ is less than that of silicon.
10. (Currently Amended) The support structure of claim 6, wherein the structure is arranged for supporting
~~the modules further comprising~~ a silicon substrate in which is formed an array of ink ejector nozzles.
11. (Original) The support structure of claim 1, wherein:
the coefficient of thermal expansion of the beam is about 2.5×10^{-6} metres per degree Celsius.

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